



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE4269GL			<b>Issued</b>	28. August 2013			
<b>MA#</b>	MA000835162							
<b>Package</b>	PG-DSO-20-35			<b>Weight*</b>	478.21 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.966	0.62	0.62	6202	6202
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75	
	non noble metal	zinc	7440-66-6	0.143	0.03		299	
	non noble metal	iron	7439-89-6	2.862	0.60		5984	
wire	non noble metal	copper	7440-50-8	116.197	24.30	24.94	242983	249341
	noble metal	gold	7440-57-5	0.398	0.08	0.08	833	833
	encapsulation	organic material	carbon black	1333-86-4	0.700	0.15		1464
encapsulation	plastics	epoxy resin	-	32.207	6.74		67350	
	inorganic material	silicondioxide	60676-86-0	317.171	66.32	73.21	663247	732061
leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5742	5742
plating	noble metal	silver	7440-22-4	1.177	0.25	0.25	2461	2461
glue	plastics	epoxy resin	-	0.402	0.08		840	
	noble metal	silver	7440-22-4	1.205	0.25	0.33	2520	3360
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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